



DSA 2026

The 13th International Conference on Dependable Systems and Their Applications

Xiamen, China, November 14-15, 2026

In 2017, the International Conference on Trustworthy Systems and Their Applications (TSA) and the International Symposium on Dependable Computing and Internet of Things (DCIT) were merged to form a larger and more comprehensive event, the International Conference on Dependable Systems and Their Applications (DSA). DSA 2026 marks the tenth edition of the conference since this successful merger, reflecting a decade of continued growth and collaboration within the scientific community. Both TSA and DCIT were technically sponsored by IEEE, and DSA 2026 continues this tradition. Building upon the strong foundations established by its predecessor conferences, DSA serves as an important forum for the presentation and discussion of innovative methodologies, techniques, tools, and management practices aimed at developing dependable and trustworthy systems and applications in a cost-effective manner. In particular, DSA 2026 highlights the growing role of emerging technologies, including artificial intelligence (AI), machine learning, deep learning, and large language models (LLMs), in advancing the state of the art in system dependability, reliability, security, and trustworthiness. The conference provides an excellent opportunity for academic researchers, industry practitioners, and government policymakers and decision-makers to exchange ideas and research results, share experiences and best practices, and explore innovative solutions to current and future challenges in the field. DSA 2026 will be held in Xiamen, China, on November 14–15, 2026.

TOPICS OF INTEREST

- ◆ Algorithms, Architecture, Framework, Design Patterns, and Maintenance for Dependable Systems and Software
- ◆ AI and ML/DL-based Techniques for System Dependability
- ◆ Dependability of Generative AI
- ◆ Security, Threats, Privacy, Safety, and Risk Management
- ◆ Dependability and Reliability Modeling and Measurement
- ◆ Requirements, Process, Standards, Productivity, and Project Management
- ◆ Quality Assurance, Maintenance, Reverse Engineering, and Re-Engineering
- ◆ Verification, Validation, and Testing
- ◆ Analysis, Debugging, Model Checking, and Program Repair
- ◆ Metrics, Measurement, and Quality Assessment
- ◆ Communication, Networking, Optimization, and Performance
- ◆ Fault Tolerance, Survivability, Resilience, and Availability
- ◆ Collaborative, Distributed, Embedded, Real-Time, High Performance, Highly Dependable, Intelligent, and Multimedia Systems
- ◆ Big Data and Analysis
- ◆ Prognostics and Health Management
- ◆ IoT, Supply Chain, Cyber-Physical Systems, Industry 4.0, and Smart City
- ◆ Empirical Studies, Benchmarking, and Industrial Best Practices
- ◆ Applications and Tools and Automation
- ◆ Approaching Artificial Creativity

IMPORTANT DATES

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|----------------------|-------------------------------------|------------------------|-------------------------|
| ◆ September 01, 2026 | Regular & Short Papers due | ◆ October 25, 2026 | Camera-ready due |
| ◆ October 01, 2026 | Workshop Papers due | ◆ October 25, 2026 | Author registration due |
| ◆ October 01, 2026 | Fast Abstracts & Industry Track due | ◆ November 14-15, 2026 | Conference dates |
| ◆ October 18, 2026 | Author notification | | |

SUBMISSION

There are five types of submissions:

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|------------------|----------|------------------|----------|
| ◆ Regular Paper | 12 pages | ◆ Fast Abstract | 2 pages |
| ◆ Short Paper | 10 pages | ◆ Workshop Paper | 10 pages |
| ◆ Industry Paper | 2 pages | | |

Submit original manuscripts (not published or considered elsewhere). Each submission should include a title, the name and affiliation of each author, an abstract, and up to 6 keywords. The format must follow the [DSA proceedings format](#). At least one Best Paper Award will be presented. Detailed instructions for paper submission can be found at <https://dsa26.techconf.org/submission>.

CONFERENCE PROCEEDINGS & SPECIAL ISSUES OF SCI JOURNALS

Conference proceedings will be published by the IEEE Conference Publishing Services (CPS). Papers in the proceedings will be submitted for inclusion in the IEEE Xplore and to all of the A&I (abstracting and indexing) partners (such as the Ei Compendex and Scopus). These papers will also appear in Google Scholar and the DBLP database.

ORGANIZING COMMITTEE

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GENERAL INQUIRIES

For more detailed and updated information, please refer to <https://dsa.techconf.org/>. For paper submission, review or other questions, please send emails to the [DSA Secretariat](#).